



Material Content Data Sheet



Sales Product Name		BBY 56-02V H6327		Issued		16. January 2020		
MA#		MA001179696						
Package		PG-SC79-2-1		Weight*		1.68 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		35	
	noble metal	gold	7440-57-5	0.006	0.35		3453	
	inorganic material	silicon	7440-21-3	0.050	2.95	3.30	29496	32984
leadframe	inorganic material	silicon	7440-21-3	0.000	0.01		92	
	non noble metal	titanium	7440-32-6	0.001	0.05		458	
	non noble metal	chromium	7440-47-3	0.002	0.14		1374	
	non noble metal	copper	7440-50-8	0.767	45.61	45.81	456133	458057
wire	non noble metal	copper	7440-50-8	0.007	0.39	0.39	3913	3913
encapsulation	organic material	carbon black	1333-86-4	0.007	0.42		4201	
	plastics	epoxy resin	-	0.120	7.14		71420	
	inorganic material	silicondioxide	60676-86-0	0.579	34.45	42.01	344497	420118
leadfinish	non noble metal	tin	7440-31-5	0.055	3.24	3.24	32446	32446
plating	noble metal	silver	7440-22-4	0.088	5.25	5.25	52482	52482
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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